

AG302-63

InGaP HBT Gain Block



Product Features

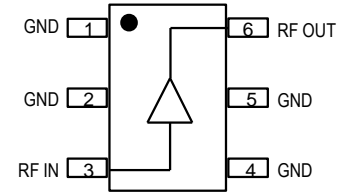
- DC – 6000 MHz
- 15.5 dB Gain @ 900 MHz
- +13.5 dBm P1dB @ 900 MHz
- +26.5 dBm OIP3 @ 900 MHz
- Single Voltage Supply
- Internally matched to 50 Ω
- Robust 1000V ESD, Class 1C
- Lead-free/green/RoHS-compliant SOT-363 package

Product Description

The AG302-63 is a general-purpose buffer amplifier that offers high dynamic range in a low-cost surface-mount package. At 900 MHz, the AG302-63 typically provides 15.5 dB gain, +26.5 dBm OIP3, and +13.5 dBm P1dB. The device combines dependable performance with consistent quality to maintain MTTF values exceeding 1000 years at mounting temperatures of +85 °C and is housed in a lead-free/green/RoHS-compliant SOT-363 industry standard SMT package.

The AG302-63 consists of a Darlington-pair amplifier using the high reliability InGaP/GaAs HBT process technology and only requires DC-blocking capacitors, a bias resistor, and an inductive RF choke for operation.

Functional Diagram



| Function | Pin No. |
|-------------|------------|
| Input | 3 |
| Output/Bias | 6 |
| Ground | 1, 2, 4, 5 |

Applications

- Mobile Infrastructure
- CATV / FTTH
- WLAN / ISM
- RFID
- WiMAX / WiBro

The broadband MMIC amplifier can be directly applied to various current and next generation wireless technologies such as GPRS, GSM, CDMA, and W-CDMA. In addition, the AG302-63 will work for other various applications within the DC to 6 GHz frequency range such as CATV and WiMAX.

Specifications ⁽¹⁾

| Parameter | Units | Min | Typ | Max |
|---------------------------|-------|------|-------|------|
| Operational Bandwidth | MHz | DC | | 6000 |
| Operational Temperature | °C | -40 | 25 | +85 |
| Test Frequency | MHz | | 900 | |
| Gain | dB | | 15.6 | |
| Input Return Loss | dB | | 18 | |
| Output Return Loss | dB | | 18 | |
| Output P1dB | dBm | | +13.4 | |
| Output IP3 ⁽²⁾ | dBm | | +26.4 | |
| Output IP2 | dBm | | +37 | |
| Noise Figure | dB | | 3.4 | |
| Test Frequency | MHz | | 1900 | |
| Gain | dB | 13.5 | 14.5 | 15.5 |
| Output P1dB | dBm | | +12.2 | |
| Output IP3 ⁽²⁾ | dBm | | +24.8 | |
| Device Voltage | V | | 4.23 | |
| Device Current | mA | | 35 | |

1. Test conditions: T = 25 °C, Supply Voltage = +5 V, R_{bias} = 22.1 Ω, 50 Ω System.
 2. 3OIP measured with two tones at an output power of -2 dBm/tone separated by 10 MHz. The suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule.

Operation of this device above any of these parameters may cause permanent damage.

Typical Performance ⁽¹⁾

| Parameter | Units | Typical | | | |
|--------------|-------|---------|-------|-------|-------|
| Frequency | MHz | 500 | 900 | 1900 | 2140 |
| S21 | dB | 15.9 | 15.6 | 14.5 | 14.2 |
| S11 | dB | -18 | -18 | -18 | -18 |
| S22 | dB | -20 | -18 | -18 | -15 |
| Output P1dB | dBm | +13.2 | +13.4 | +12.2 | +11.7 |
| Output IP3 | dBm | +26.6 | +26.4 | +24.8 | +24.3 |
| Noise Figure | dB | 3.3 | 3.4 | 3.6 | 3.6 |

Absolute Maximum Rating

| Parameter | Rating |
|-------------------------------------|----------------|
| Storage Temperature | -55 to +125 °C |
| DC Voltage | +4.5 V |
| RF Input Power (continuous) | +10 dBm |
| Thermal Resistance, R _{th} | 325°C/W |
| For 10 ⁶ hours MTTF | |
| Junction Temperature | +177°C |

Ordering Information

| Part No. | Description |
|-------------|--|
| AG302-63G | InGaP HBT Gain Block (lead-free/green/RoHS-compliant SOT-363 Package) |
| AG302-63PCB | 700 – 2400 MHz Fully Assembled Eval. Board |

Standard tape / reel size = 3000 pieces on a 7" reel

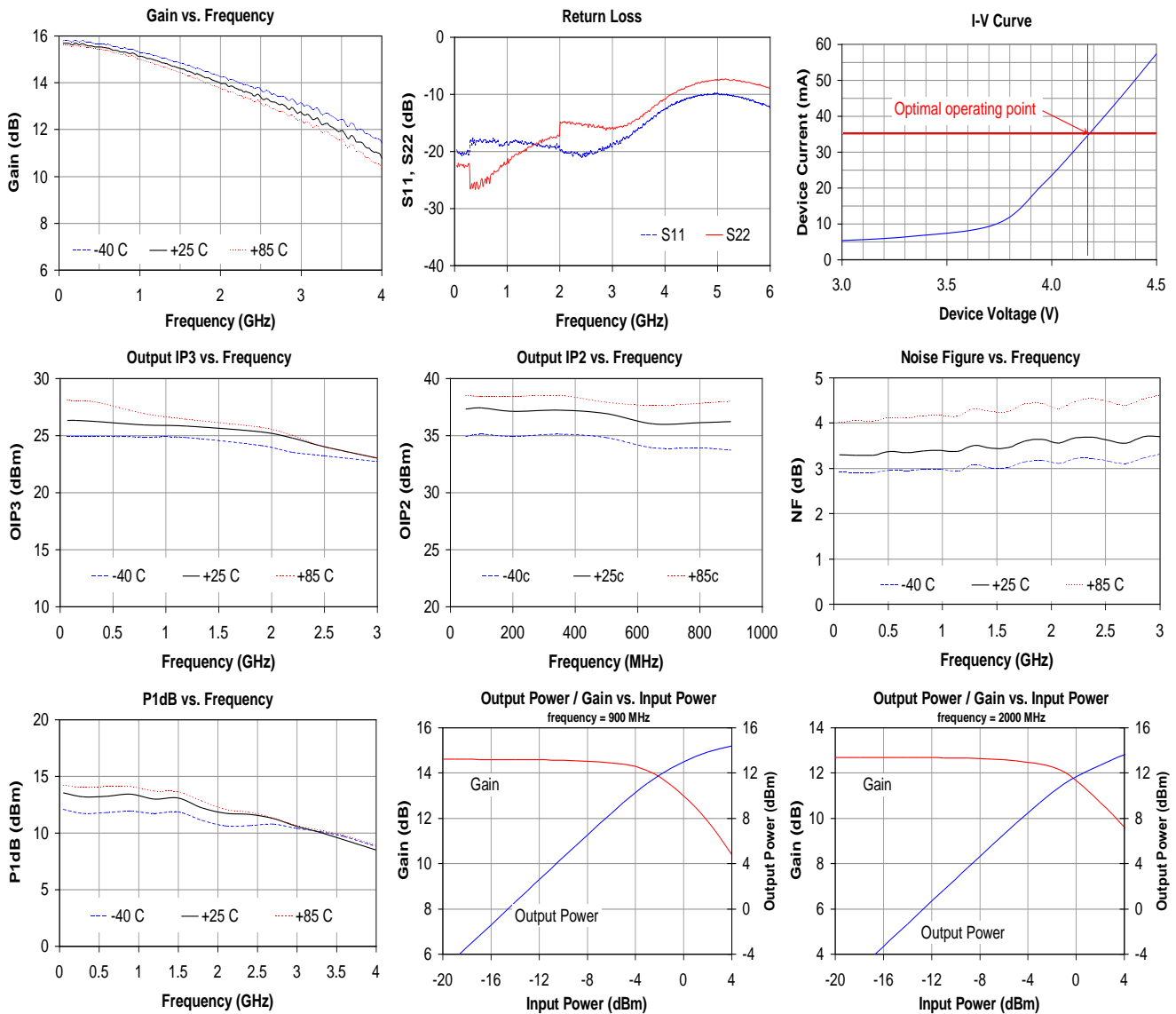
Specifications and information are subject to change without notice

Typical Device RF Performance

Supply Bias = +5 V, $R_{bias} = 22.1 \Omega$, $I_{cc} = 35 \text{ mA}$

| Frequency | MHz | 100 | 500 | 900 | 1900 | 2140 | 2400 | 3500 | 5800 |
|--------------|-----|-------|-------|-------|-------|-------|-------|------|------|
| S21 | dB | 16.0 | 15.9 | 15.6 | 14.5 | 14.2 | 13.9 | 12.5 | 9.2 |
| S11 | dB | -18 | -18 | -18 | -18 | -18 | -18 | -15 | -11 |
| S22 | dB | -20 | -20 | -18 | -18 | -15 | -15 | -14 | -8 |
| Output P1dB | dBm | +13.5 | +13.2 | +13.4 | +12.2 | +11.7 | +11.6 | +9.5 | |
| Output IP3 | dBm | +26.6 | +26.6 | +26.4 | +24.8 | +24.3 | +23.9 | | |
| Noise Figure | dB | 3.3 | 3.3 | 3.4 | 3.6 | 3.6 | 3.7 | | |

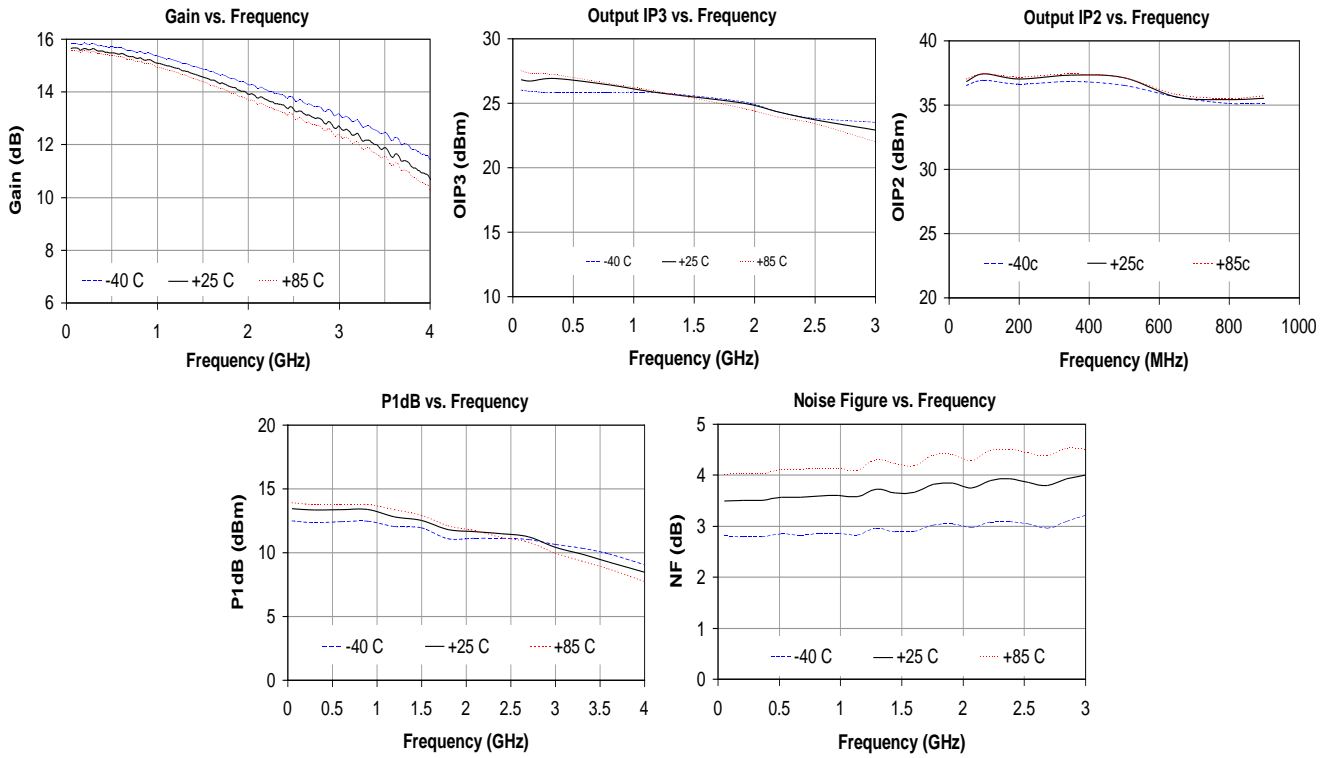
1. Test conditions: $T = 25^\circ\text{C}$, Supply Voltage = +5 V, Device Voltage = 4.23 V, $R_{bias} = 22.1 \Omega$, $I_{cc} = 35 \text{ mA}$ typical, 50 Ω System.
2. 3OIP measured with two tones at an output power of -2 dBm/tone separated by 10 MHz. The suppression on the largest IM3 product is used to calculate the 3OIP using a 2:1 rule.
3. Data is shown as device performance only. Actual implementation for the desired frequency band will be determined by external components shown in the application circuit.



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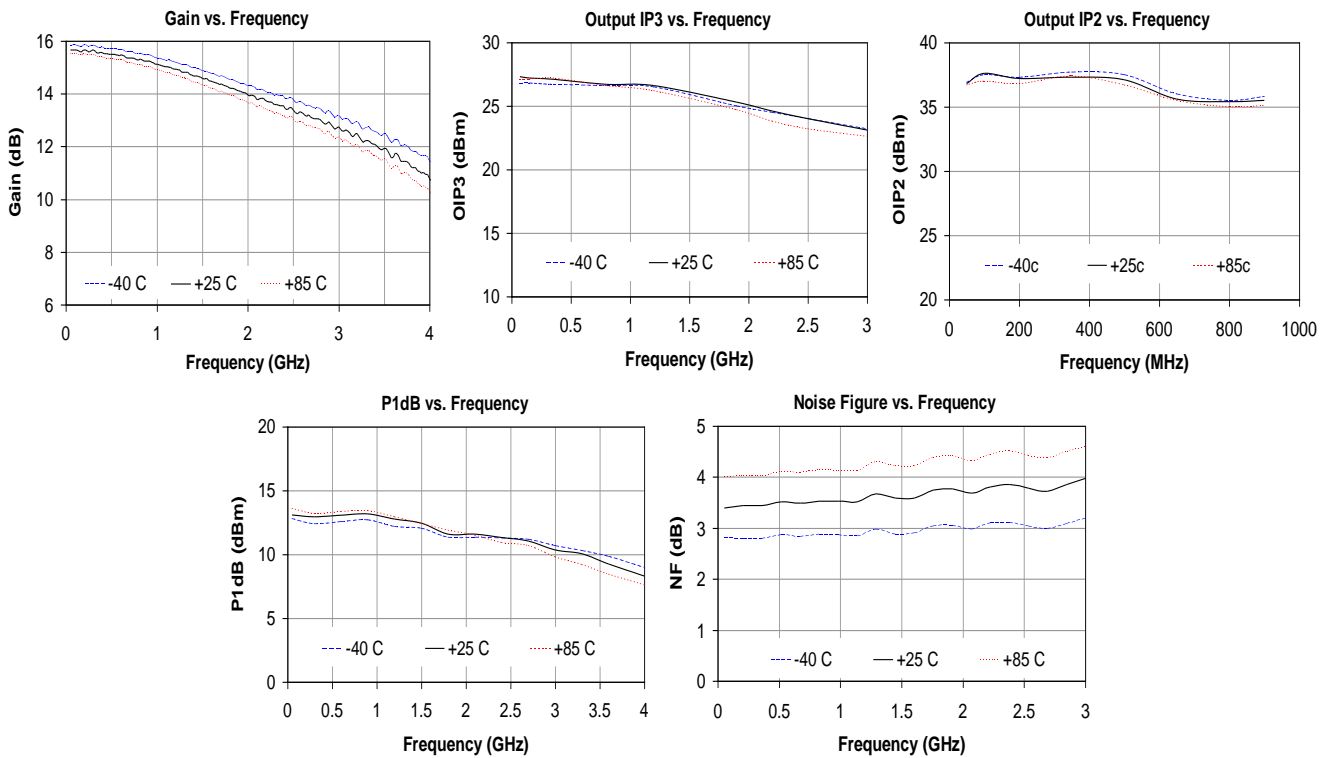
Typical Device RF Performance (cont'd)

Supply Bias = +6 V, $R_{bias} = 51 \Omega$, $I_{cc} = 35 \text{ mA}$



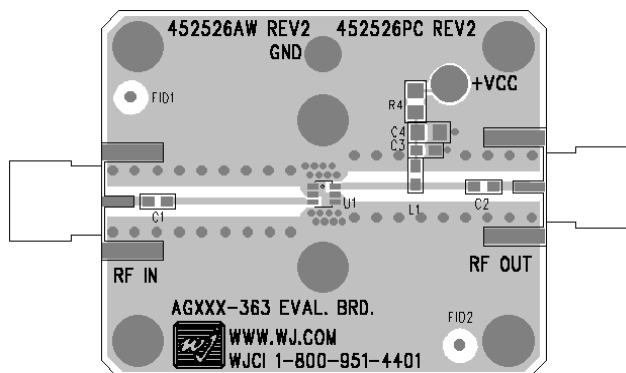
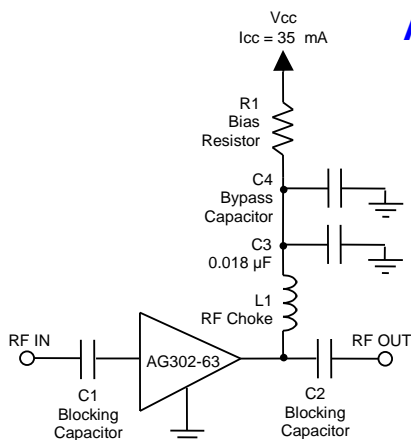
Typical Device RF Performance

Supply Bias = +8 V, $R_{bias} = 108 \Omega$, $I_{cc} = 35 \text{ mA}$



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Application Circuit



Recommended Component Values

| Reference Designator | Frequency (MHz) | | | | | | |
|----------------------|-----------------|---------|--------|-------|-------|-------|-------|
| | 50 | 500 | 900 | 1900 | 2200 | 2500 | 3500 |
| L1 | 820 nH | 220 nH | 68 nH | 27 nH | 22 nH | 18 nH | 15 nH |
| C1, C2, C4 | .018 µF | 1000 pF | 100 pF | 68 pF | 68 pF | 56 pF | 39 pF |

- The proper values for the components are dependent upon the intended frequency of operation.
- The following values are contained on the evaluation board to achieve optimal broadband performance:

| Ref. Desig. | Value / Type | Size |
|-------------|--------------------------|------|
| L1 | 39 nH wirewound inductor | 0603 |
| C1, C2 | 56 pF chip capacitor | 0603 |
| C3 | 0.018 µF chip capacitor | 0603 |
| C4 | Do Not Place | |
| R1 | 22.1 Ω 1% tolerance | 0805 |

Recommended Bias Resistor Values

| Supply Voltage | R1 value | Size |
|----------------|-----------|------|
| 5 V | 22.1 ohms | 0603 |
| 6 V | 51 ohms | 0805 |
| 7 V | 80 ohms | 1206 |
| 8 V | 108 ohms | 1210 |
| 9 V | 137 ohms | 1210 |
| 10 V | 166 ohms | 1210 |
| 12 V | 223 ohms | 2010 |

The proper value for R1 is dependent upon the supply voltage and allows for bias stability over temperature. WJ recommends a minimum supply bias of +5 V. A 1% tolerance resistor is recommended.

Typical Device Data

S-Parameters ($V_{device} = +4.23$ V, $I_{CC} = 35$ mA, $T = 25$ °C, calibrated to device leads)

| Freq (MHz) | S11 (dB) | S11 (ang) | S21 (dB) | S21 (ang) | S12 (dB) | S12 (ang) | S22 (dB) | S22 (ang) |
|------------|----------|-----------|----------|-----------|----------|-----------|----------|-----------|
| 50 | -19.85 | -177.05 | 15.79 | 177.89 | -19.50 | 1.85 | -22.57 | -9.39 |
| 250 | -19.98 | 175.72 | 15.72 | 170.42 | -19.97 | 1.77 | -22.62 | -20.70 |
| 500 | -18.01 | 168.09 | 15.61 | 160.75 | -19.89 | -1.49 | -25.70 | -57.42 |
| 750 | -18.03 | 161.31 | 15.46 | 151.46 | -19.75 | -0.83 | -23.67 | -81.31 |
| 1000 | -18.40 | 155.28 | 15.23 | 142.64 | -20.03 | -5.40 | -21.92 | -97.33 |
| 1250 | -18.41 | 151.47 | 15.04 | 133.43 | -19.57 | -3.15 | -20.29 | -113.22 |
| 1500 | -18.66 | 151.02 | 14.72 | 124.92 | -19.70 | -3.55 | -19.00 | -123.83 |
| 1750 | -19.00 | 148.77 | 14.42 | 116.42 | -19.61 | -2.45 | -17.99 | -133.36 |
| 2000 | -19.53 | 143.58 | 14.09 | 108.45 | -19.21 | -4.88 | -17.12 | -142.08 |
| 2250 | -20.76 | 113.17 | 13.77 | 100.67 | -19.05 | -5.29 | -15.05 | -130.60 |
| 2500 | -20.87 | 111.03 | 13.52 | 95.18 | -19.25 | -9.57 | -15.35 | -142.08 |
| 2750 | -19.68 | 123.77 | 13.23 | 87.31 | -18.88 | -8.74 | -15.64 | -156.85 |
| 3000 | -19.28 | 129.86 | 12.90 | 79.66 | -18.52 | -7.78 | -15.96 | -175.61 |
| 3250 | -17.79 | 131.49 | 12.55 | 72.44 | -18.46 | -10.45 | -15.54 | 163.89 |
| 3500 | -15.90 | 129.32 | 12.20 | 64.86 | -18.38 | -12.94 | -14.38 | 142.50 |
| 3750 | -14.24 | 123.22 | 11.76 | 57.50 | -18.15 | -16.94 | -12.52 | 126.50 |
| 4000 | -12.67 | 119.37 | 11.34 | 49.91 | -17.95 | -17.17 | -10.93 | 117.72 |
| 4250 | -11.41 | 115.92 | 10.89 | 43.03 | -17.83 | -21.16 | -9.42 | 109.93 |
| 4500 | -10.59 | 112.56 | 10.41 | 36.71 | -17.67 | -22.91 | -8.57 | 104.82 |
| 4750 | -10.10 | 109.83 | 9.99 | 30.18 | -17.43 | -25.99 | -7.86 | 102.35 |
| 5000 | -9.85 | 106.48 | 9.64 | 24.37 | -17.45 | -26.81 | -7.45 | 102.33 |
| 5250 | -10.24 | 105.44 | 9.33 | 19.39 | -17.45 | -29.65 | -7.63 | 102.18 |
| 5500 | -10.79 | 104.94 | 9.06 | 14.78 | -16.94 | -30.74 | -7.77 | 103.04 |
| 5750 | -11.50 | 106.52 | 8.93 | 9.92 | -16.70 | -31.15 | -8.37 | 104.38 |
| 6000 | -12.41 | 105.88 | 8.77 | 4.74 | -16.46 | -33.40 | -9.03 | 103.86 |

Device S-parameters are available for download from the website at: <http://www.TriQuint.com>

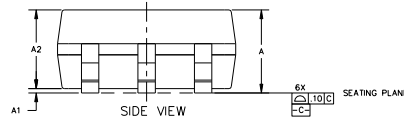
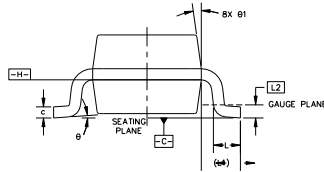
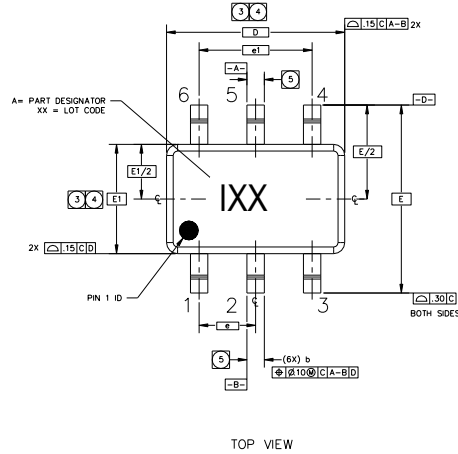
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Mechanical Information

This package is lead-free/Green/RoHS-compliant. It is compatible with both lead-free (maximum 260 °C reflow temperature) and leaded (maximum 245 °C reflow temperature) soldering processes. The plating material on the leads is annealed matte tin over copper.

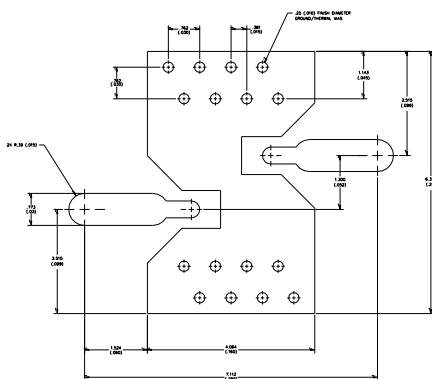
Outline Drawing

| SYMBOL | MIN | MAX |
|--------|-------------------|----------------|
| A | - | 1.10 (.043) |
| A1 | 0 | .10 (.004) |
| A2 | .70 (.028) | 1.00 (.039) |
| D | 2.00 (.079) | BASIC |
| E | 2.10 (.083) | BASIC |
| E1 | 1.25 (.039) | BASIC |
| L | .41 (.016) | .41 (.016) |
| L1 | .42 REF (.017) | |
| L2 | .15 (.006) | BASIC |
| θ | 0° | 8° |
| θ1 | 4° | 12° |
| b | .15 (.006) | .30 (.012) |
| c | .08 (.003) | .22 (.009) |
| e | .65 (.026) | BASIC |
| e1 | 1.30 (.051) | BASIC |



- NOTES:
- DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1194. PACKAGE CONFORMS TO JEDEC MO-203, ISSUE B.
 - DIMENSIONS ARE IN MILLIMETERS (INCHES).
 - DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER END. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 mm PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM H.
 - THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, GATE BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND THE BOTTOM OF THE PLASTIC BODY. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM H.
 - DATUM A & B TO BE DETERMINED AT DATUM H.
 - DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR IS NOT LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.

Land Pattern



Product Marking

The component will be marked with an "I" designator followed by a two-digit numeric code on the top surface of the package.

Tape and reel specifications for this part are located on the website in the "Application Notes" section.

MSL / ESD Rating



Caution! ESD sensitive device.

ESD Rating: Class 1C
 Value: Passes ≥ 1000V min.
 Test: Human Body Model (HBM)
 Standard: JEDEC Standard JESD22-A114

ESD Rating: Class IV
 Value: Passes ≥ 1000V min.
 Test: Charged Device Model (CDM)
 Standard: JEDEC Standard JESD22-C101

MSL Rating: Level 3 at +260 °C convection reflow
 Standard: JEDEC Standard J-STD-020

Mounting Config. Notes

- Ground / thermal vias are critical for the performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
- Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via region contacts the heatsink.
- Do not put solder mask on the backside of the PC board in the region where the board contacts the heatsink.
- RF trace width depends upon the PC board material and construction.
- Use 1 oz. Copper minimum.
- All dimensions are in millimeters (inches). Angles are in degrees.

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- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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